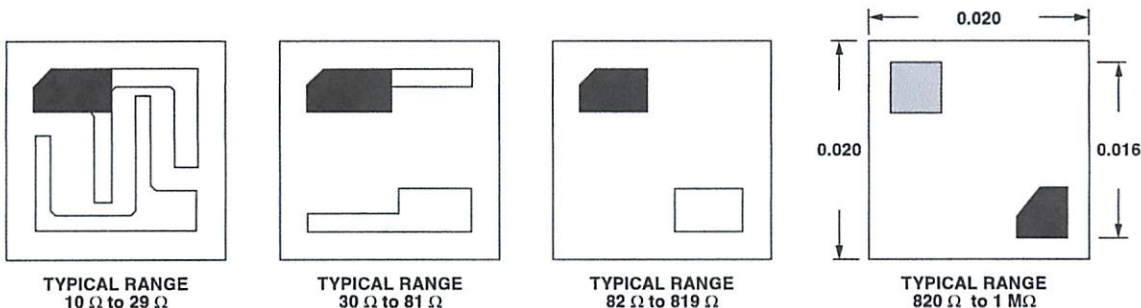




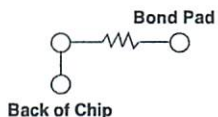
DIMENSIONS in inches



Note

- Notched shaded area represents top bonding pad. The backside of the chip constitutes the second resistor connection.

SCHEMATIC

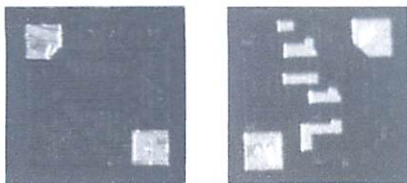


MECHANICAL SPECIFICATIONS	
PARAMETER	VALUE
Chip Size	0.020" x 0.020" ± 0.002" (0.50 mm x 0.50 mm ± 0.05 mm)
Chip Thickness	0.010" ± 0.003" (0.253 mm ± 0.05 mm)
Chip Substrate Material	Oxidized silicon, 10 kÅ minimum SiO ₂
Resistor Material	Tantalum nitride, self-passivating
Bonding Pad Size	0.004" x 0.004" (0.100 mm x 0.100 mm)
Number of Pads	1
Pad Material	10 kÅ minimum aluminum (15 kÅ minimum gold optional)
Backing	3 kÅ minimum gold
Recommended Attachment Method	Eutectic or conductive epoxy

GLOBAL PART NUMBER INFORMATION												
Global Part Number: BCR50000FKAHWS												
Global Part Number Description: BCR 5K 1 %, 100 ppm/°C, Al term., Class H, WS												
B	C	R	5	0	0	0	F	K	A	H	W	S
MODEL	RESISTANCE	RESISTANCE MULTIPLIER CODE	TOLERANCE CODE	TCR (ppm/°C)	TERMINATION	VISUAL CLASS (per MIL-STD-883, Method 2032)	PACKAGING					
BCR 20 x 20 size back contact resistor	First 4 digits are significant figures of resistance	B = 0.01 A = 0.1 0 = 1 1 = 10 2 = 100 3 = 1000	B = 0.1 % C = 0.25 % D = 0.5 % F = 1.0 % G = 2.0 % J = 5.0 % K = 10 %	E = ± 25 C = ± 50 K = ± 100 M = ± 250 R = 0/- 250	G = Gold A = Aluminum	H = Class H K = Class K	WS = Waffle pack 100 min./mult.					
Historical Part Number: WBCR02750000F (will continue to be accepted)												



Thin Film, Back-Contact Resistor



Product may not be to scale

The Back Contact Resistor (BCR) series single-value back-contact resistor chip is one of the smallest chips available.

The BCR requires only one wire bond thus saving hybrid space.

The BCRs are manufactured using Vishay Electro-Films (EFI) sophisticated thin film equipment and manufacturing technology. The BCRs are 100 % electrically tested and visually inspected to MIL-STD-883, method 2032 class H or K.

FEATURES

- Wire bondable
- Only one wire bond required
- Small size: 0.020 inches square
- Resistance range: 10 Ω to 1 MΩ
- Oxidized silicon substrate for good power dissipation
- Resistor material: Tantalum nitride, self-passivating
- Moisture resistant
- Case size: 0202
- Material categorization: For definitions of compliance please see www.vishay.com/doc?99912

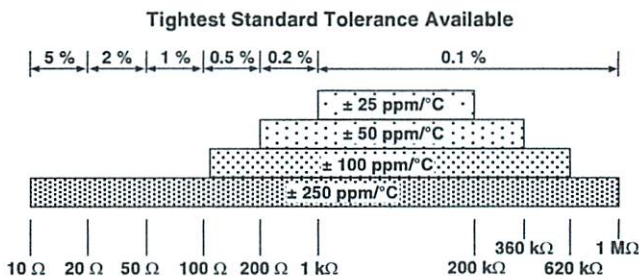


RoHS COMPLIANT GREEN (S-2008)

APPLICATIONS

Vishay EFI BCR resistor chips are widely used in hybrid packages where space is limited. The bottom connection is made by attaching the back of the chip to the substrate either eutectically or with conductive epoxy. The single wire bond is made to the notched pad on the top of the chip. (The other rectangular pad on the top of the chip is a via hole, a low-ohmic contact connecting the resistor to the bottom of the chip.)

TEMPERATURE COEFFICIENT OF RESISTANCE, VALUES, AND TOLERANCES		
PARAMETER	VALUE	UNIT
Total Resistance Range	10 to 1M	Ω
Standard Tolerances	± 0.1, ± 0.2, ± 0.5, ± 1, ± 2, ± 5	%
TCR	± 25, ± 50, ± 100, ± 250	ppm/°C



STANDARD ELECTRICAL SPECIFICATIONS		
PARAMETER	VALUE	UNIT
Noise, MIL-STD-202, Method 308 100 Ω to 250 kΩ < 100 Ω or > 251 kΩ	- 35 typ. - 20 typ.	dB
Moisture resistance, MIL-STD-202, Method 106	± 0.5 max. ΔR/R	%
Stability, 1000 h, + 125 °C, 125 mW	± 1.0 max. ΔR/R	%
Operating Temperature Range	- 55 to + 125	°C
Thermal Shock, MIL-STD-202, Method 107, Test Condition F	± 0.25 max. ΔR/R	%
High Temperature Exposure, + 150 °C, 100 h	± 0.5 max. ΔR/R	%
Dielectric Voltage Breakdown	200	V
Insulation Resistance	10 ¹² min.	Ω
Operating Voltage	75 max.	V
DC Power Rating at + 70 °C (Derated to zero at + 175 °C)	0.250	W
5 x Rated Power Short-Time Overload, + 25 °C, 5 s	± 0.25 max. ΔR/R	%